

# 41A  
5-26-00  
R. Proder

PATENT  
Docket No.: M4065.0135/P135

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Terry Gilton et al.

Serial No.: 09/285,668

Filed: April 5, 1999

For: METHOD OF FORMING A  
METAL SEED LAYER FOR  
SUBSEQUENT PLATING

Assistant Commissioner for Patents  
Washington, D.C. 20231



Group Art Unit: 2814

Examiner: T. Quach

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AMENDMENT

Dear Sir:

In response to the Office Action dated February 15, 2000, please amend the  
above-identified U.S. patent application as follows:

In the Claims:

Please amend the claims as follows:

1. (Amended) A method of plating a metal layer on a substrate, comprising the steps of:  
  
providing a substrate;  
  
forming a barrier layer, containing a reducing agent, on a top surface of the  
  
substrate;

05/17/2000 NLJANG 00000008 09285668 72.00 OP  
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